

AMENDMENT TRANSMITTAL LETTER (Large Entity)

Applicant(s): Consuelo N. Tangpuz et al.

Docket No.

11948.26

Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/678,010	October 2, 2003	T.T. Ho	27,966	2818	9241

Invention: **METHOD FOR MAINTAINING SOLDER THICKNESS IN FLIPCHIP ATTACH PACKAGING PROCESSES**

APR 15 2005

COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	25 -	39 =	0	x \$50.00	\$0.00
INDEP. CLAIMS	6 -	8 =	0	x \$200.00	\$0.00
Multiple Dependent Claims (check if applicable)	<input type="checkbox"/>				\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- No additional fee is required for amendment.
- Please charge Deposit Account No. _____ in the amount of _____.
- A check in the amount of _____ to cover the filing fee is enclosed.
- The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account 50-0843
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Dated: April 11, 2005

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on

April 11, 2005

(Date)

John Bawden

Signature of Person Mailing Correspondence

JoAnn Bawden

Typed or Printed Name of Person Mailing Correspondence



Serial No. 10/678,010
Attorney Docket No. 11948.0026

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application:
Consuelo N. Tangpuz et al.

Serial No.: 10/678,010

Filed: October 2, 2003

For: METHOD FOR MAINTAINING
SOLDER THICKNESS IN FLIPCHIP
ATTACH PACKAGING PROCESSES

Confirmation No. 9241

Group Art Unit: 2818

Examiner: Ho, Tu-Tu

Mail Stop Non-Final Response
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT AND REQUEST FOR RECONSIDERATION
UNDER 35 U.S.C. §§ 1.111 & 1.115

In response to the Office Action dated January 10, 2005, Applicant respectfully requests reconsideration of this application and in light of the following amendments and remarks.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450, on this 11th Day of April 2005.

Signed: John Bawol

4/11/2005